

SEARCH FOR SOMETHING

by

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SEARCH FOR SOMETHING

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my abstract

“... *Josefa.*

“...*laca.*”

yo y tu.

“...*come lady come.*”

pa darte.

to Nenas and nenita

ACKNOWLEDGMENTS

Many people has contributed to make this work possible that it is impossible to name them all.

Table of Contents

List of Figures	vii
List of Tables	viii
1 Introduction	1
2 The LHC Accelerator and the CMS Experiment	2
2.1 The LHC Accelerator	2
2.2 CMS	3
2.2.1 The Tracker Detector	4
2.2.2 The Electromagnetic Calorimeter	4
2.2.3 The Hadronic Calorimeter	4
2.2.4 The Muon Chambers	4
3 The SM and BSM Theories	5
4 Event generation, simulation and reconstruction	6
5 Search for the particle	7
6 More on the Analysis?	8

7 Module Production for the Phase I CMS Pixel Detector Upgrade	9
7.1 The CMS Pixel Detector Phase I Upgrade	10
7.2 Module Production at UNL	12
7.2.1 Visual Inspections	13
7.2.2 IV Test	14
7.2.3 Gluing	15
7.2.4 Wirebonding	15
7.2.5 Encapsulation	15
7.2.6 Electrical Test of a Fully assembly Module	15
8 Beam Test of the RD53 chip for CMS Pixel Detector Upgrade Phase 2	19
8.1 Introduction	19
8.2 The RD53 Chip	19
8.3 Purpose of Test Beam	19
8.4 Test Beam Set Up	19
8.5 Results	19
9 Conclusions	20
9.1 Analysis	20
9.2 Phase 1	20
9.3 Beam Test	20
Bibliography	20
References	21

List of Figures

2.1	The CERN acceleration <i>facilities</i>	3
2.2	CMS cross sectional view	3
2.3	CMS cross sectional view	4
2.4	CMS cross sectional view	4
7.1	Expected performance of the original pixel detector for different luminosities.	11
7.2	Layout of the upgraded and old pixel detectors.	11
7.3	UNL module assembly workflow.	12
7.4	Photograph of a BBM and HDI.	13
7.5	Photograph of the visual inspection and IV test station.	14
7.6	Visual inspection of a bare module.	14
7.7	bla for index.	15
7.8	bla for index.	16
7.9	bla for index.	16
7.10	bla for index.	17
7.11	Visual inspection of a bare module.	17
7.12	bla for index.	18
7.13	bla for index.	18

List of Tables

CHAPTER 1

Introduction

Talk about particle physics in general and the organization of the documents

CHAPTER 2

The LHC Accelerator and the CMS Experiment

In the 1960s Peter Higgs and others *need ref* put up the finishing touches on a theory combining three of the four fundamental forces. This theory became to be known as the Standard Model (SM) of particles physics. It predicted the existence of several particles which were discovered in the following decades. However, one particle was proving to be elusive, the so-called Higgs boson. With this in mind the European Organization for Nuclear Research (CERN) started plans to build an accelerator large enough to be able to find this elusive particle. Hence, the Large Hadron Collider (LHC) was born.

2.1 The LHC Accelerator

A circular ring of 27 Km in circumference, the LHC was built at the French-Swiss border outside Geneva, Switzerland, see figure 2.1.

Four experiments were designed and build to test different physics theories and search for undiscovered particles at the LHC. Two of them, A Toroidal Large Aparatus (ATLAS) [1] and the Compact Muon Solenoid (CMS) [2] are large multipurpose experiments. The third experiment is LHCb [3], which is specifically dedicated to study B-meson physics, the last experiment ALICE [4], A Large Ion Collider Experiment,

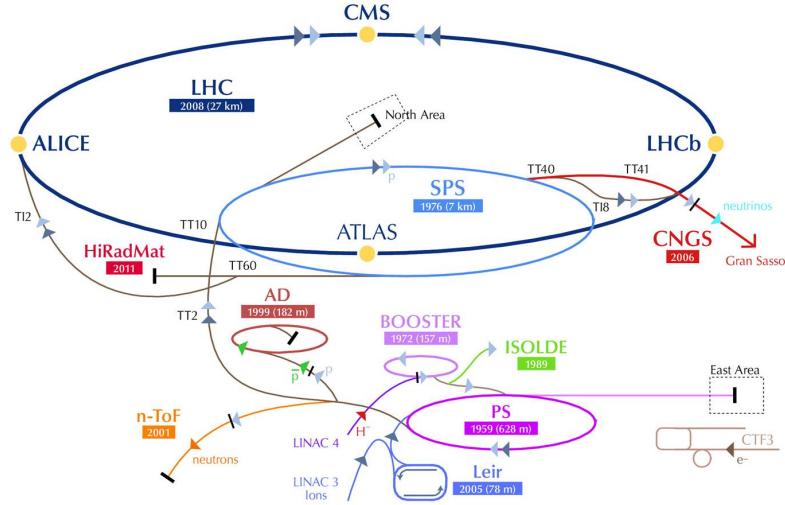


Figure 2.1: The CERN acceleration *facilities* showing the location of the four main experiment as well as the acceleration process[need ref].

was design to investigate heavy ion collisions.

2.2 CMS



Figure 2.2: CMS cross sectional view.

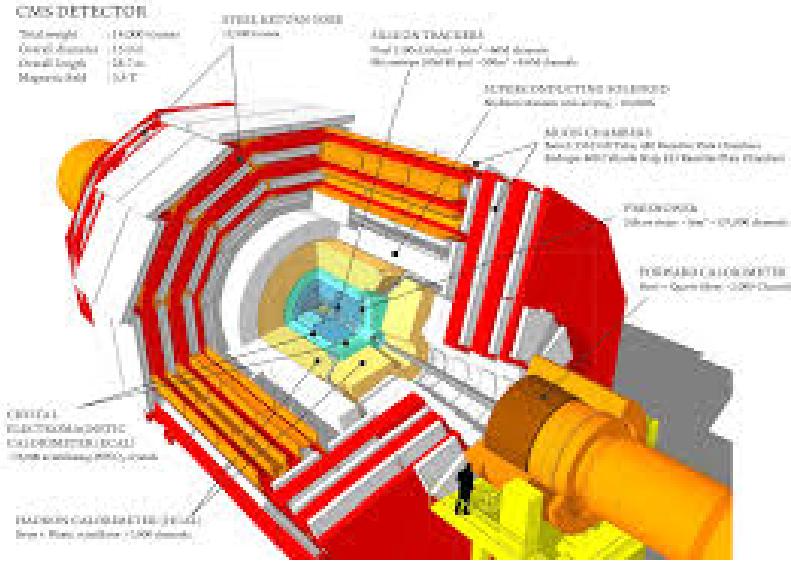


Figure 2.3: CMS cross sectional view.

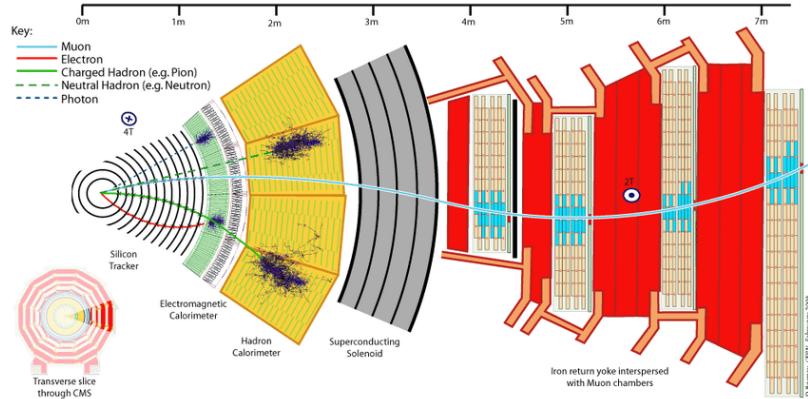


Figure 2.4: CMS cross sectional view.

2.2.1 The Tracker Detector

2.2.2 The Electromagnetic Calorimeter

2.2.3 The Hadronic Calorimeter

2.2.4 The Muon Chambers

CHAPTER 3

The SM and BSM Theories

Proposed in the 1960s the standard model of particles physics has been successful in describing many phenomena of the particle world

CHAPTER 4

Event generation, simulation and reconstruction

Description of event generation and simulation

CHAPTER 5

Search for the particle

Data analysis details

CHAPTER 6

More on the Analysis?

More?

CHAPTER 7

Module Production for the Phase I CMS Pixel Detector Upgrade

As discussed in chapter 2 the CMS pixel detector will *suffer* from radiation damage throughout its lifetime hence the need for periodical updates. The first version of the detector was known as phase 0, it became fully operational 2010 after solving a setback during the original starting period in 2008. In 2017 the pixel detector was replaced during the so-called phase 1 upgrade, the University of Nebraska, high energy group (UNL-HEP) played a major role in assembling and testing over 500 modules, from 2013 to 2016, which then became part of the forward region of the pixel detector (FPix). The next update of this detector (phase 2) is projected to take place in 2025 when the current detector will be reaching its limits. In this chapter we describe why the phase 0 pixel detector needed an upgrade making the work done by the UNL-HEP group. Some of these steps will be highlighted and described in detail as they were my contributions to this production campaign. Specially the and highlighting

7.1 The CMS Pixel Detector Phase I Upgrade

The CMS pixel detector is composed of two sections, the barrel section (BPix) and the forward section (FPix). Each of these sections (for phase 0) was composed of three layers originally designed to record three 3D positions (tracks) of the particles emerging from the pp collisions. As well as to provide information to reconstruct primary and secondary vertices of decaying particles. This detector performed well during the LHC run I,[incorporate the bunch crossing?](#) taking data at the design luminosity of $1 \times 10^{34} cm^{-2}s^{-1}$, which was then used in many analysis including the discovery of the Higgs boson published in 2013. But after a few years of operation the pixel detector started to degrade due to radiation damage, causing an increase of fake rates as well as loose on resolution. Moreover, for run II the LHC planned to double the luminosity with successive increment until reach its peak of $2 \times 10^{35} cm^{-2}s^{-1}$. A simulation of the performance of the pixel detector under different luminosity conditions can be seen in figure 7.1

This degradation prompted the need for an improved pixel detector. It was designed to have four layers in the barrel ubicated at distances of H₁=2420 and 3 layers at each endcap as shown in Fig. 7.2. better

This degradation prompted the need for an improved pixel detector. It was designed to have four layers in the barrel ubicated at distances of H_{en}a2420 and 3 layers at each endcap as shown in 7.2. better

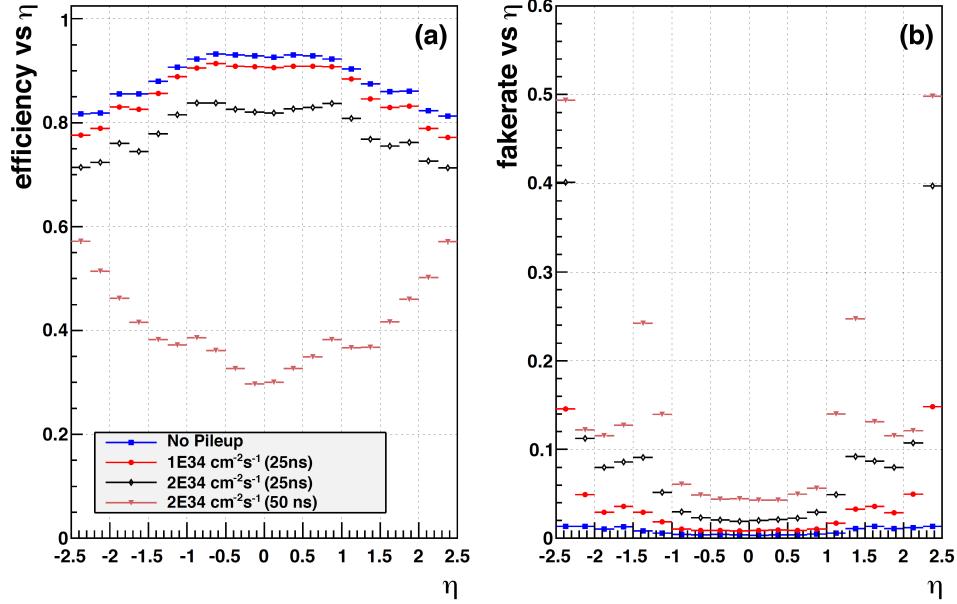


Figure 7.1: Expected performance of the original pixel detector under different luminosity conditions: a) track-finding efficiency; b) fake rate. Conventions are the same for both plots, considering zero pileup (blue squares), average pileup of 25 (red dots), average pileup of 50 (black diamonds), and average pileup of 100 (magenta triangles). [5]

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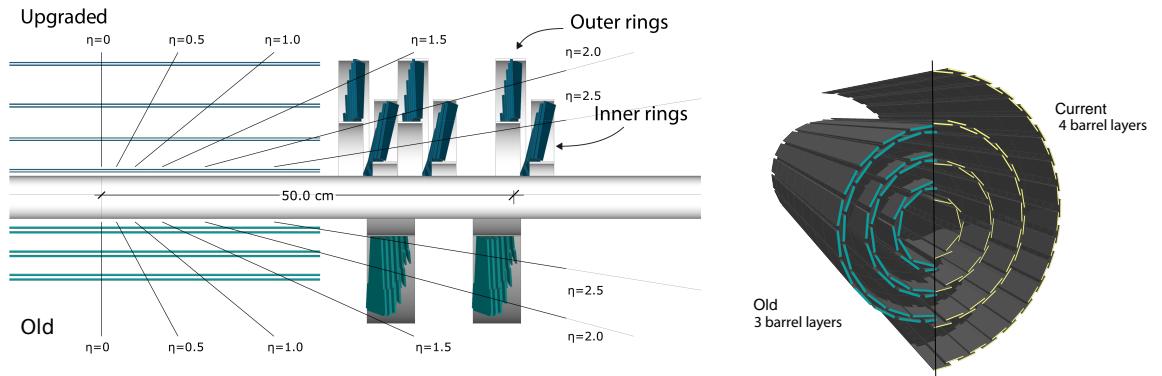


Figure 7.2: Layout and comparison of the layers and disks in the upgraded (Phase I) and old (Phase 0) pixel detectors [5].

7.2 Module Production at UNL

The UNL module production workflow was designed to follow a pipeline-like structure as shown in figure 7.3.

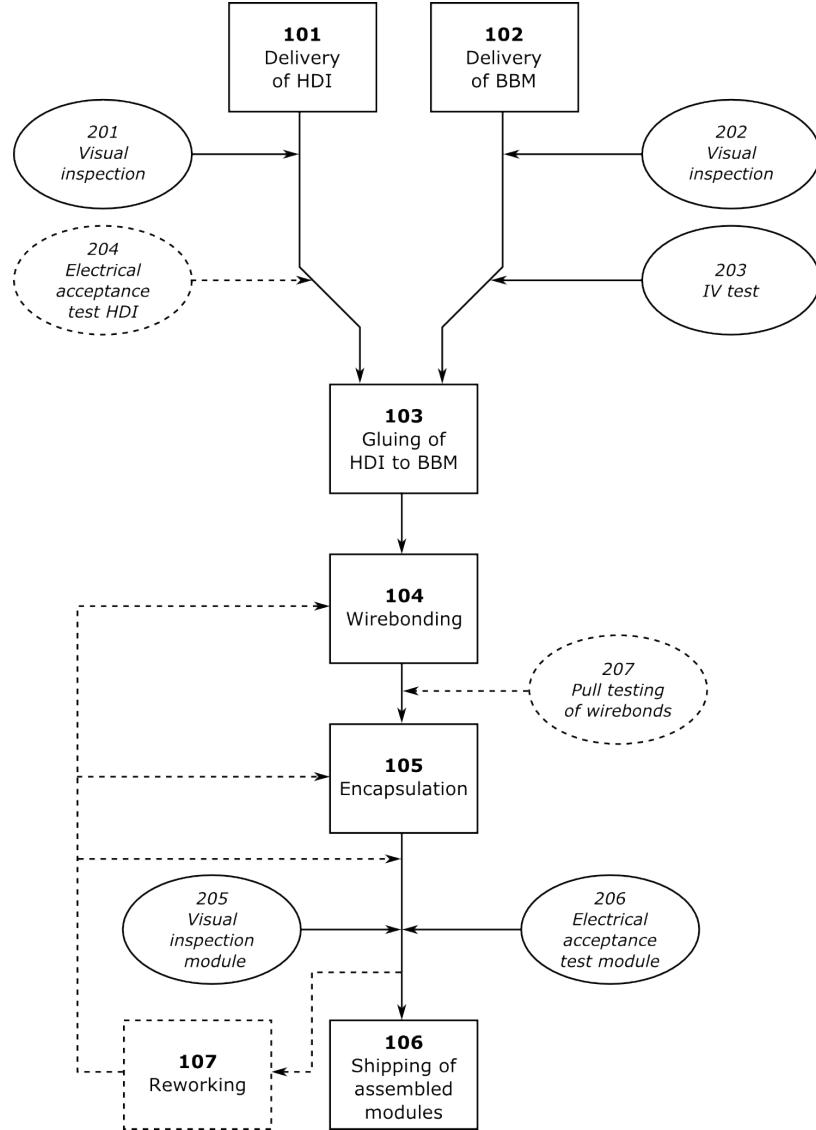


Figure 7.3: UNL module assembly workflow. Dashed lines represent occasional quality testing and reworking procedures [6].

This allows for different batches of modules to be going through it at different stages without stopping the workflow. Following is a short description of the tests

and procedures performed during the production in the UNL silicon Lab. Special emphasis will be made in IV test, visual inspection and electrical test, the stages where the author of this work made most of the work **improve**.

7.2.1 Visual Inspections

The UNL-HEP group assembly workflow started upon receiving two components: a Bare Bonded Module (BBM) and a High Density Interconnect (HDI), see figure 7.4.



Figure 7.4: Photograph of a BBM (left) and HDI (right) as received by the UNL-HEP group.

The first stage of the module production was to do a visual inspection on these components to ensure they were in good conditions and able to continue into the production pipeline. To get a good view of such a small components a powerful microscope with magnification of **confirm** and an attached camera was used. A photograph of the set up is shown in figure 7.5.

Figure 7.11 shows different parts of four different modules where defects are observed. Some of these defects (Fig 2(chipped)) will cause the module to be rejected immediately while others (Fig 3 and 4) will still undergo an IV test.

why BBM has more scratches than the HDI

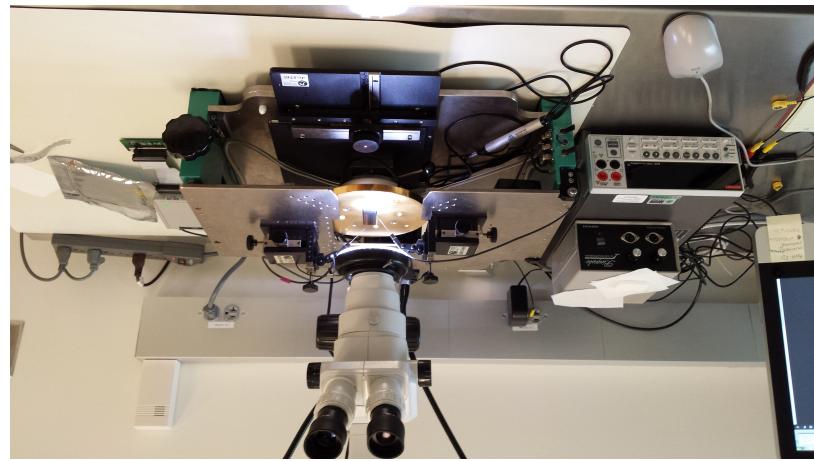


Figure 7.5: Photograph showing a BBM under the microscope during a visual inspection. This station also served as IV test stand.

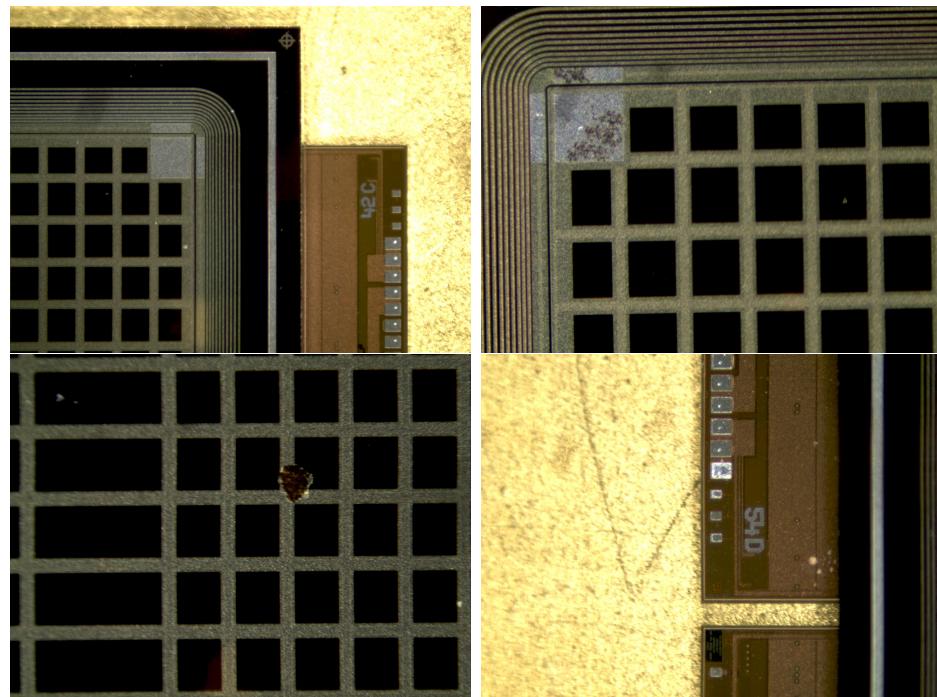


Figure 7.6: Photograph of the visual inspection of a BBM showing few of the things observed during a visual inspection: A good module (top left), scratches on the high voltage connection path (top right), scratch on the middle of the BBM (bottom left), and scratches on the wire bonds pad (bottom right)

7.2.2 IV Test

After both BBM and HDI were visually inspected

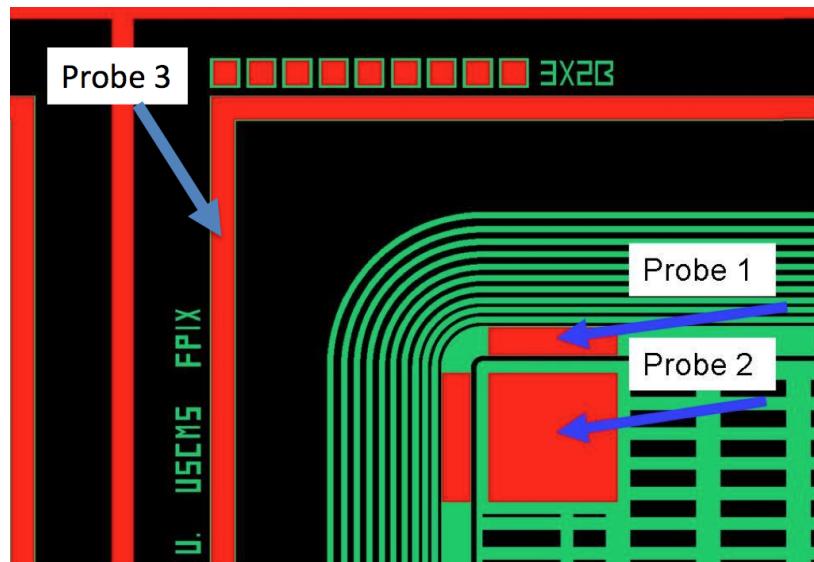


Figure 7.7: bla bla.

7.2.3 Gluing

7.2.4 Wirebonding

7.2.5 Encapsulation

7.2.6 Electrical Test of a Fully assembly Module

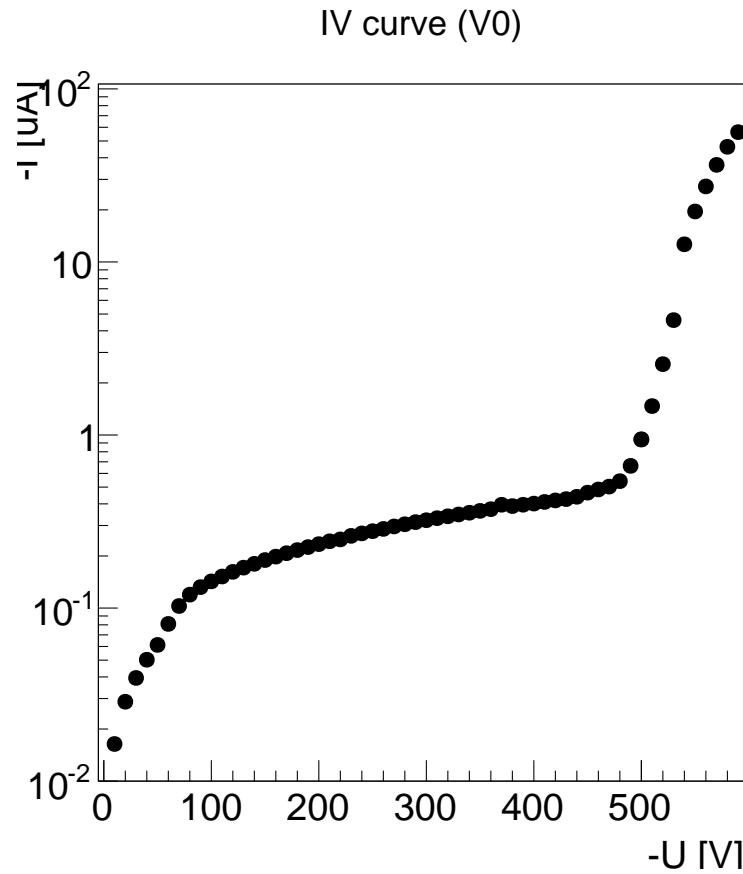


Figure 7.8: bla bla.

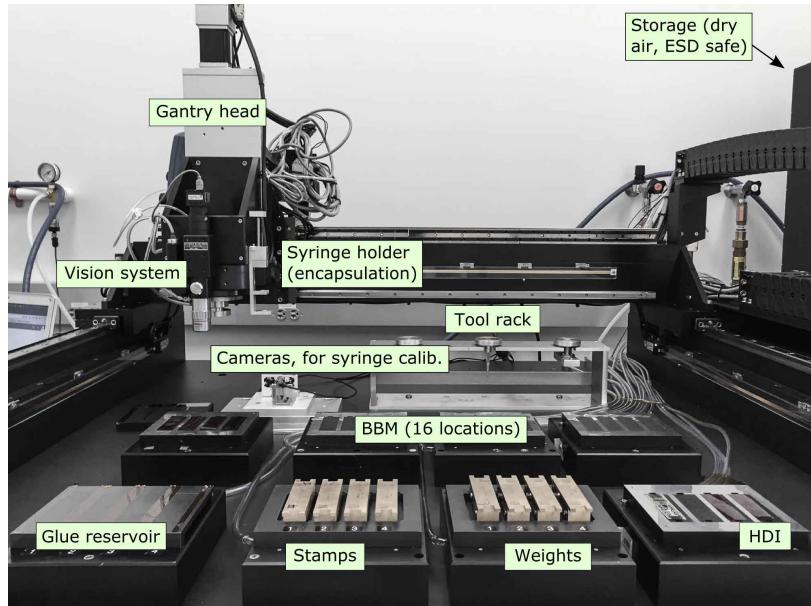


Figure 7.9: bla bla.

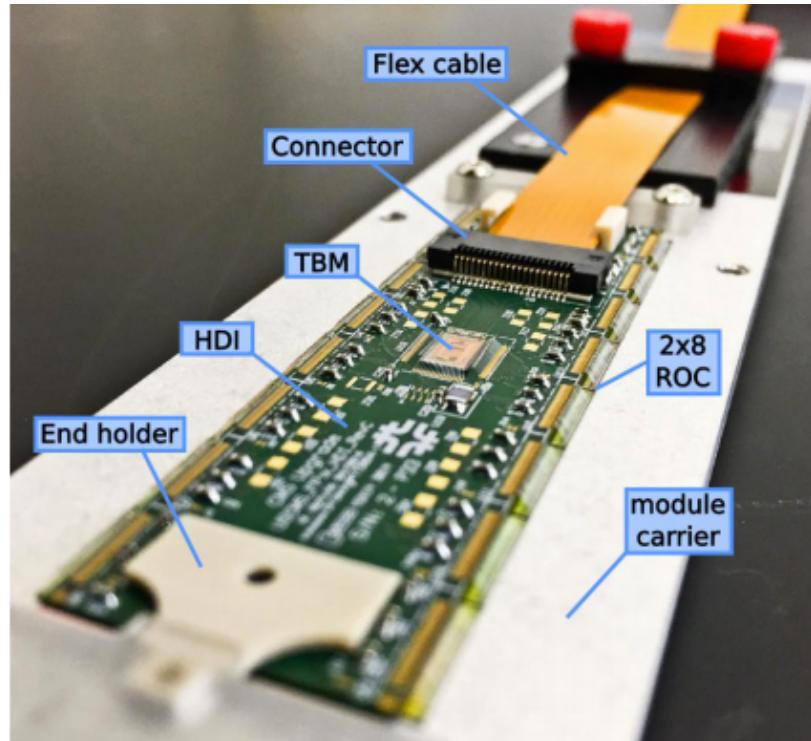


Figure 7.10: bla bla.

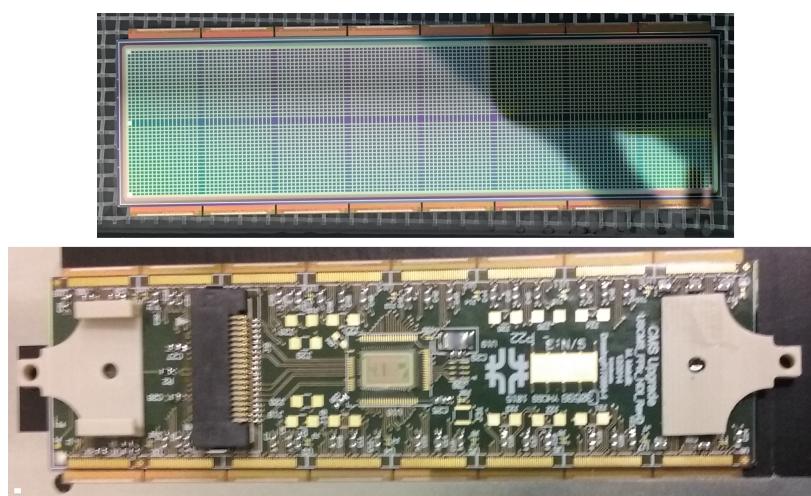


Figure 7.11: Visual inspection of a bare module.

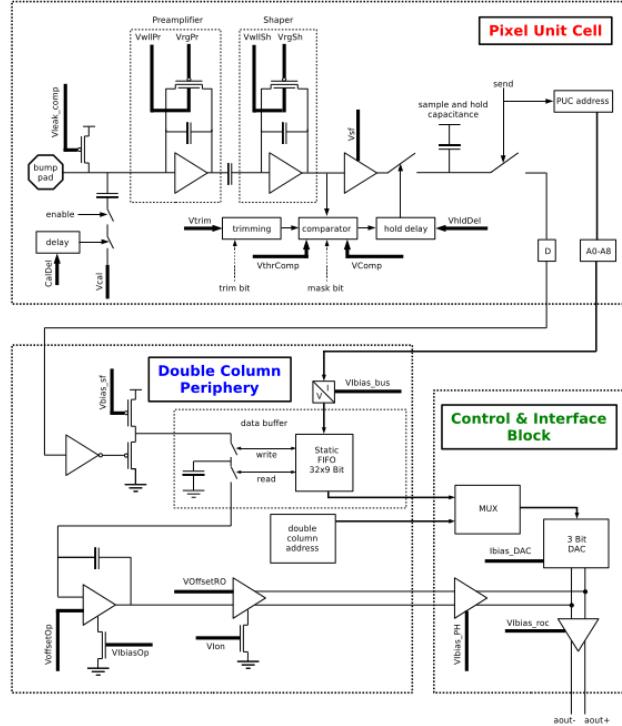


Figure 4. Schematic view of the readout chain

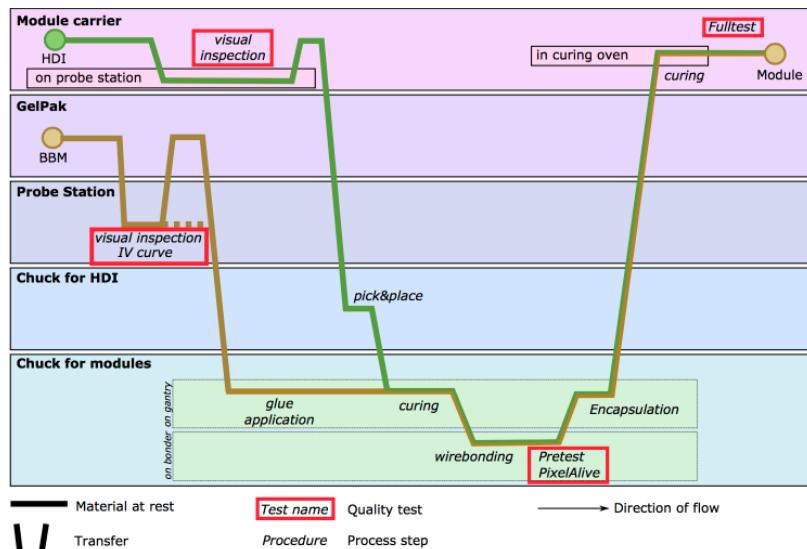
Figure 7.12: bla bla.

Figure 7.13: bla bla.

CHAPTER 8

Beam Test of the RD53 chip for CMS Pixel Detector Upgrade Phase 2

8.1 Introduction

8.2 The RD53 Chip

8.3 Purpose of Test Beam

8.4 Test Beam Set Up

8.5 Results

CHAPTER 9

Conclusions

9.1 Analysis

9.2 Phase 1

9.3 Beam Test

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